TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

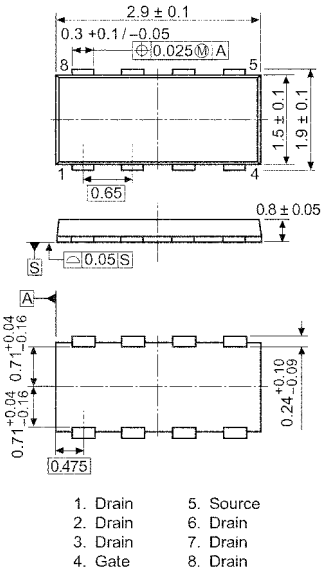
TPCF8101

Notebook PC Applications

Portable Equipment Applications

- Low drain-source ON resistance: $R_{DS\ (ON)}$ = 22 mΩ (typ.)
- High forward transfer admittance: $|Y_{fs}|$ = 14 S (typ.)
- Low leakage current: I_{DSS} = −10 μA (max) (V_{DS} = −12 V)
- Enhancement-model: V_{th} = −0.5 to −1.2 V
  (V_{DS} = −10 V, I_D = −200 μA)

Unit: mm



JEDEC	—
JEITA	—
TOSHIBA	2-3U1A

Weight: 0.011 g (typ.)

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	−12	V
Drain-gate voltage (R_{GS} = 20 kΩ)		V_{DGR}	−12	V
Gate-source voltage		V_{GSS}	±8	V
Drain current	DC (Note 1)	I_D	−6	A
	Pulsed (Note 1)	I_{DP}	−24	
Drain power dissipation (t = 5 s) (Note 2a)		P_D	2.5	W
Drain power dissipation (t = 5 s) (Note 2b)		P_D	0.7	W
Single pulse avalanche energy (Note 3)		E_{AS}	6.3	mJ
Avalanche current		I_{AR}	−3	A
Repetitive avalanche energy (Note 4)		E_{AR}	0.25	mJ
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	−55~150	°C

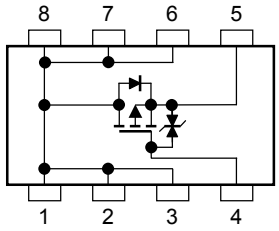
Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	$R_{th\ (ch-a)}$	50.0	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	$R_{th\ (ch-a)}$	178.6	°C/W

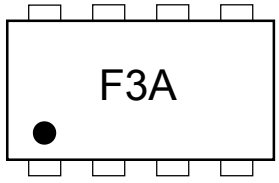
Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

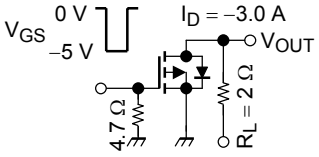
Circuit Configuration



Marking (Note 5)



Electrical Characteristics (Ta = 25°C)

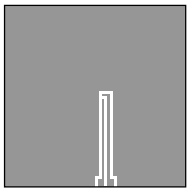
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	V_{GS} = ±8 V, V_{DS} = 0 V	—	—	±10	μA
Drain cut-off current		I_{DSS}	V_{DS} = −12 V, V_{GS} = 0 V	—	—	−10	μA
Drain-source breakdown voltage		$V_{(BR)\ DSS}$	I_D = −10 mA, V_{GS} = 0 V	−12	—	—	V
		$V_{(BR)\ DSX}$	I_D = −10 mA, V_{GS} = 8 V	−4	—	—	
Gate threshold voltage		V_{th}	V_{DS} = −10 V, I_D = −200 μA	−0.5	—	−1.2	V
Drain-source ON resistance		$R_{DS\ (ON)}$	V_{GS} = −1.8 V, I_D = −1.5 A	—	60	85	mΩ
		$R_{DS\ (ON)}$	V_{GS} = −2.5 V, I_D = −3.0 A	—	32	40	
		$R_{DS\ (ON)}$	V_{GS} = −4.5 V, I_D = −3.0 A	—	22	28	
Forward transfer admittance		$\|Y_{fs}\|$	V_{DS} = −10 V, I_D = −3.0 A	7	14	—	S
Input capacitance		C_{iss}	V_{DS} = −10 V, V_{GS} = 0 V, f = 1 MHz	—	1600	—	pF
Reverse transfer capacitance		C_{rss}		—	260	—	
Output capacitance		C_{oss}		—	335	—	
Switching time	Rise time	t_r	 Duty ≦ 1%, t_w = 10 μs	—	7	—	ns
	Turn-on time	t_{on}		—	13	—	
	Fall time	t_f		—	21	—	
	Turn-off time	t_{off}		—	68	—	
Total gate charge (gate-source plus gate-drain)		Q_g	V_{DD} ≃ −10 V, V_{GS} = −5 V, I_D = −6.0 A	—	18.0	—	nC
Gate-source charge		Q_{gs}		—	14.5	—	
Gate-drain (“miller”) charge		Q_{gd}		—	3.5	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	I_{DRP}	—	—	—	−24	A
Forward voltage (diode)		V_{DSF}	I_{DR} = −6.0 A, V_{GS} = 0 V	—	—	1.2	V

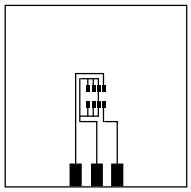
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



FR-4
25.4 × 25.4 × 0.8
Unit: (mm)

(a)



FR-4
25.4 × 25.4 × 0.8
Unit: (mm)

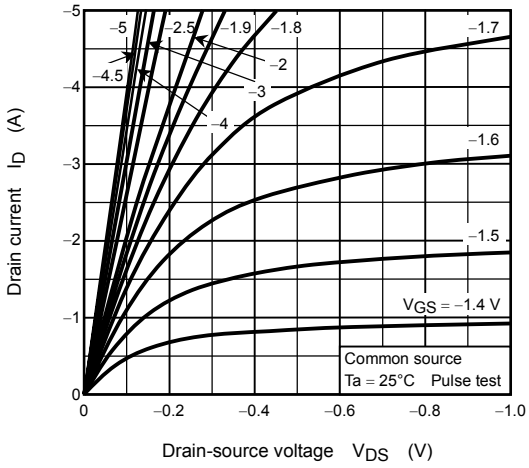
(b)

Note 3: V_{DD} = −10 V, T_{ch} = 25°C (initial), L = 0.5 mH, R_G = 25 Ω, I_{AR} = −3.0 A

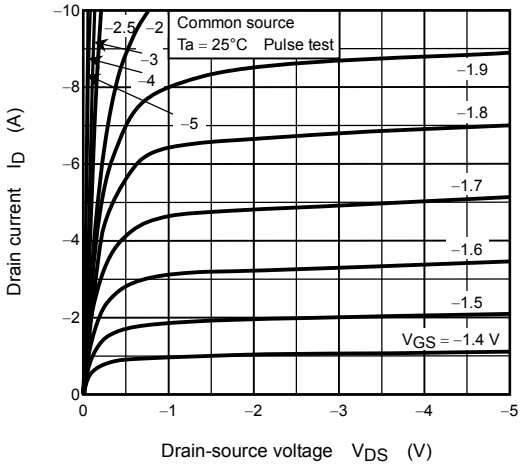
Note 4: Repetitive rating: pulse width limited by Max. Channel temperature.

Note 5: Black round marking “●” locates on the left lower side of parts number “F3A” indicates terminal No.1.

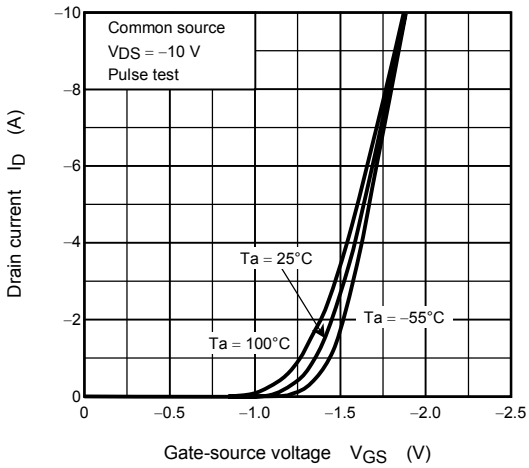
$I_D - V_{DS}$



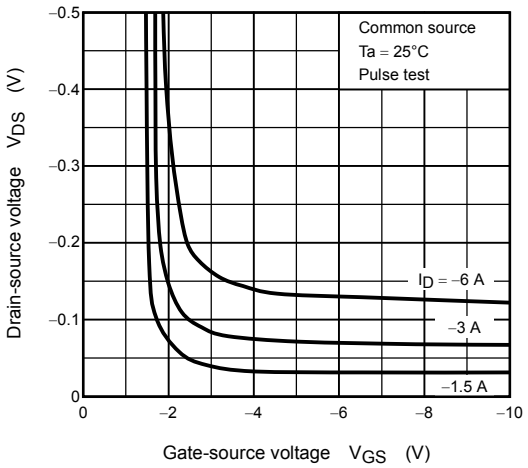
$I_D - V_{DS}$



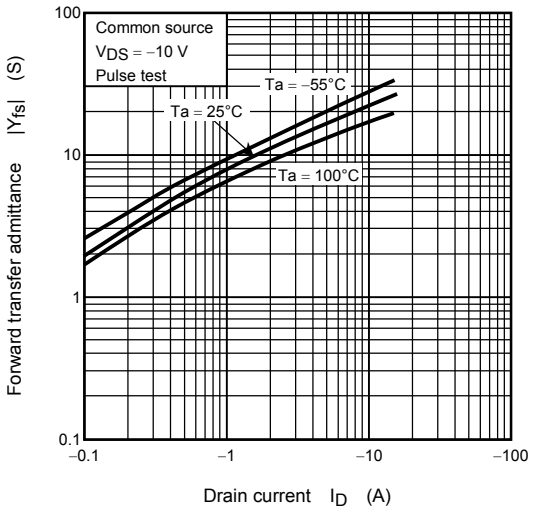
$I_D - V_{GS}$



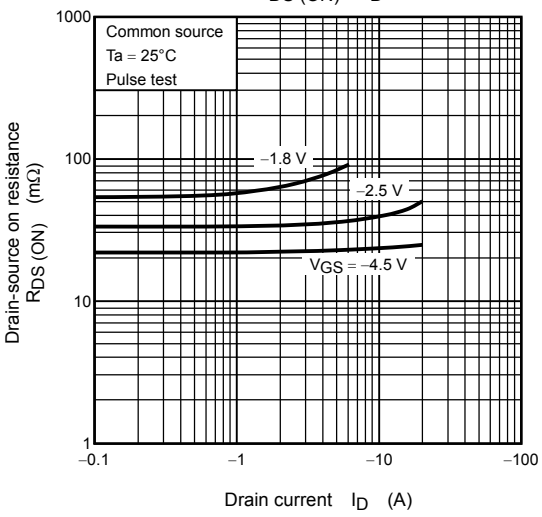
$V_{DS} - V_{GS}$



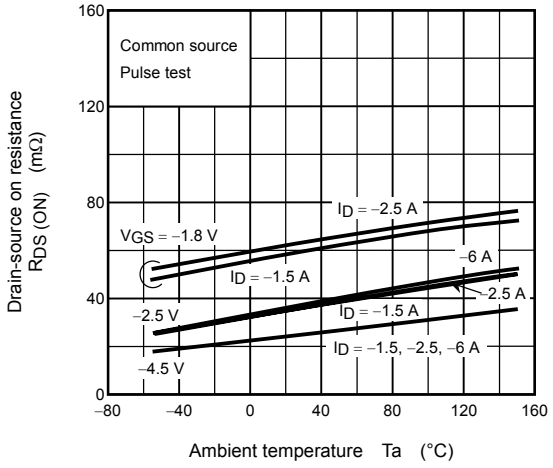
$|Y_{fs}| - I_D$



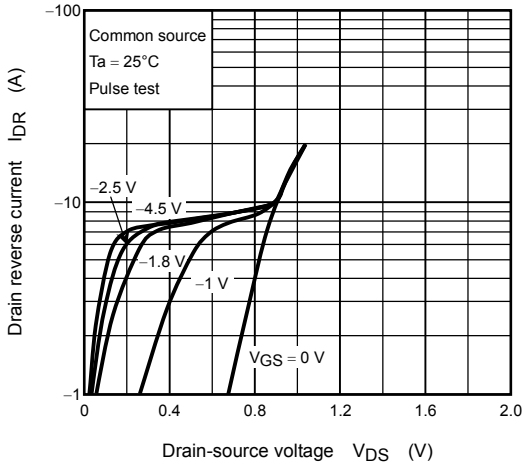
$R_{DS\ (ON)} - I_D$



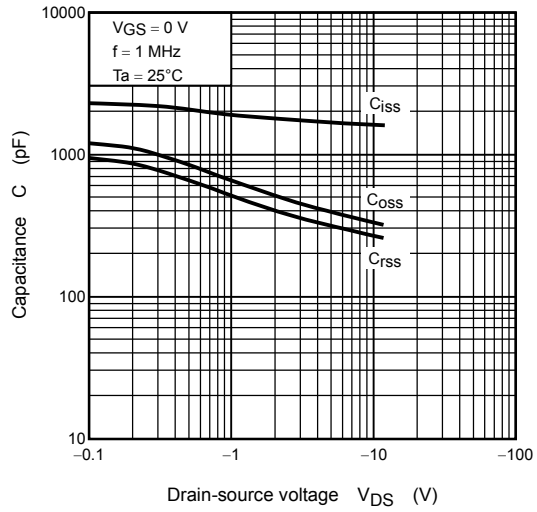
$R_{DS\ (ON)}$ – Ta



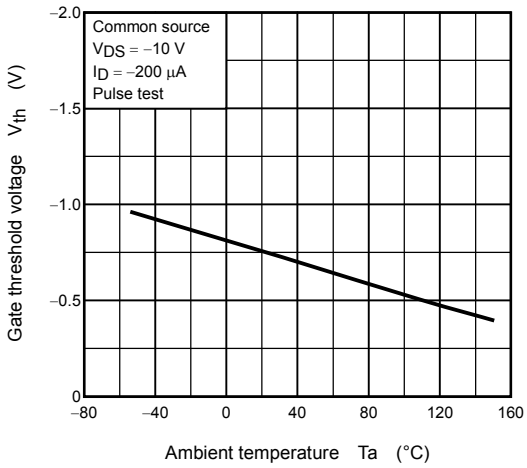
I_{DR} – V_{DS}



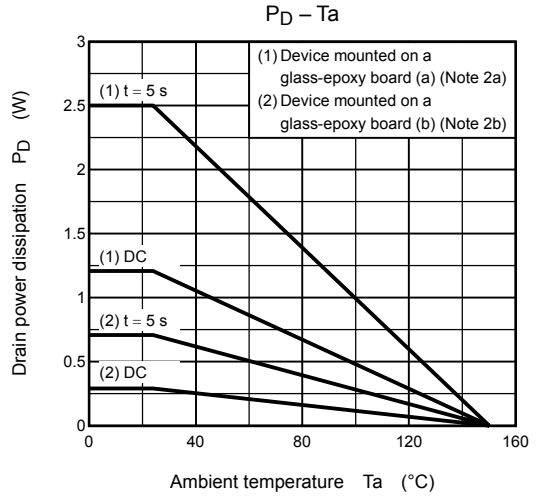
Capacitance – V_{DS}



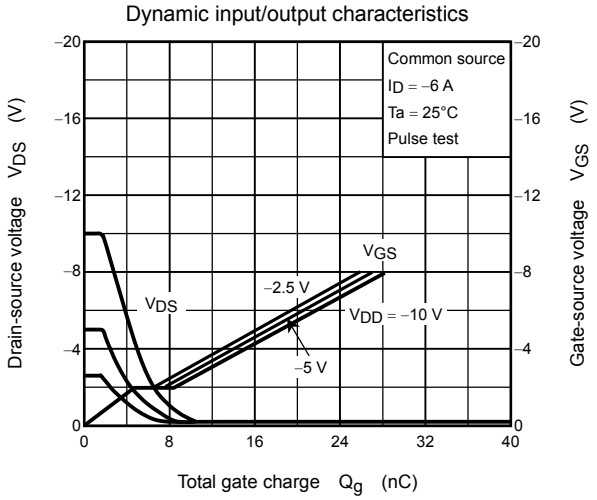
V_{th} – Ta



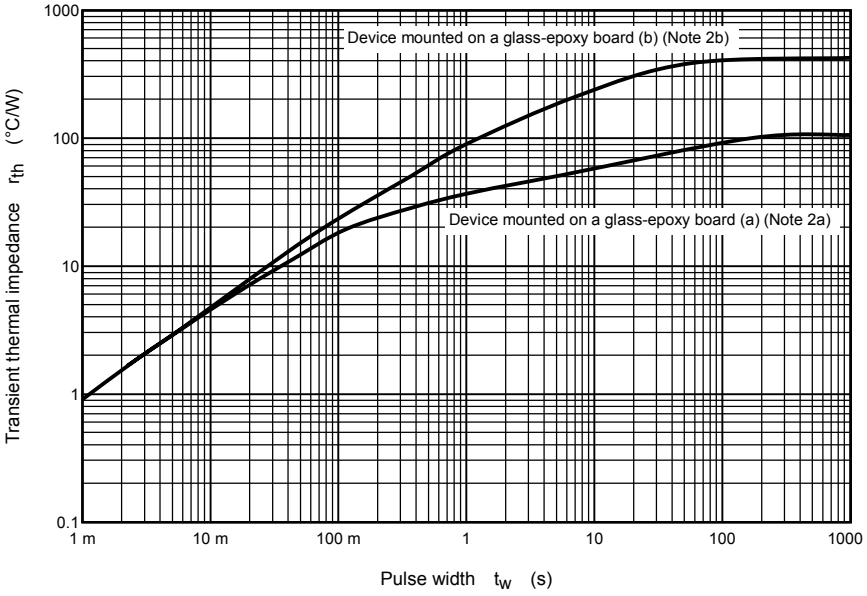
P_D – Ta



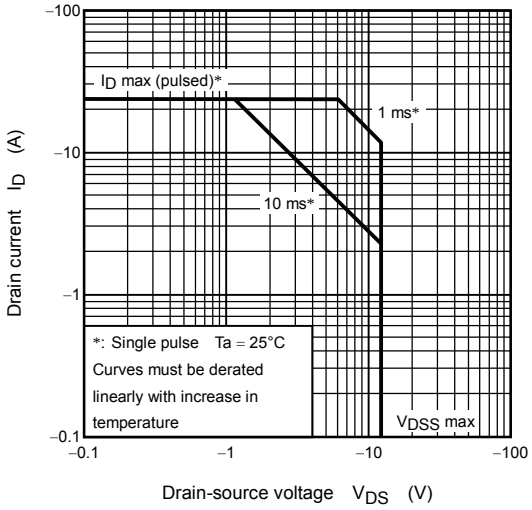
Dynamic input/output characteristics



$r_{th} - t_w$



Safe operating area



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